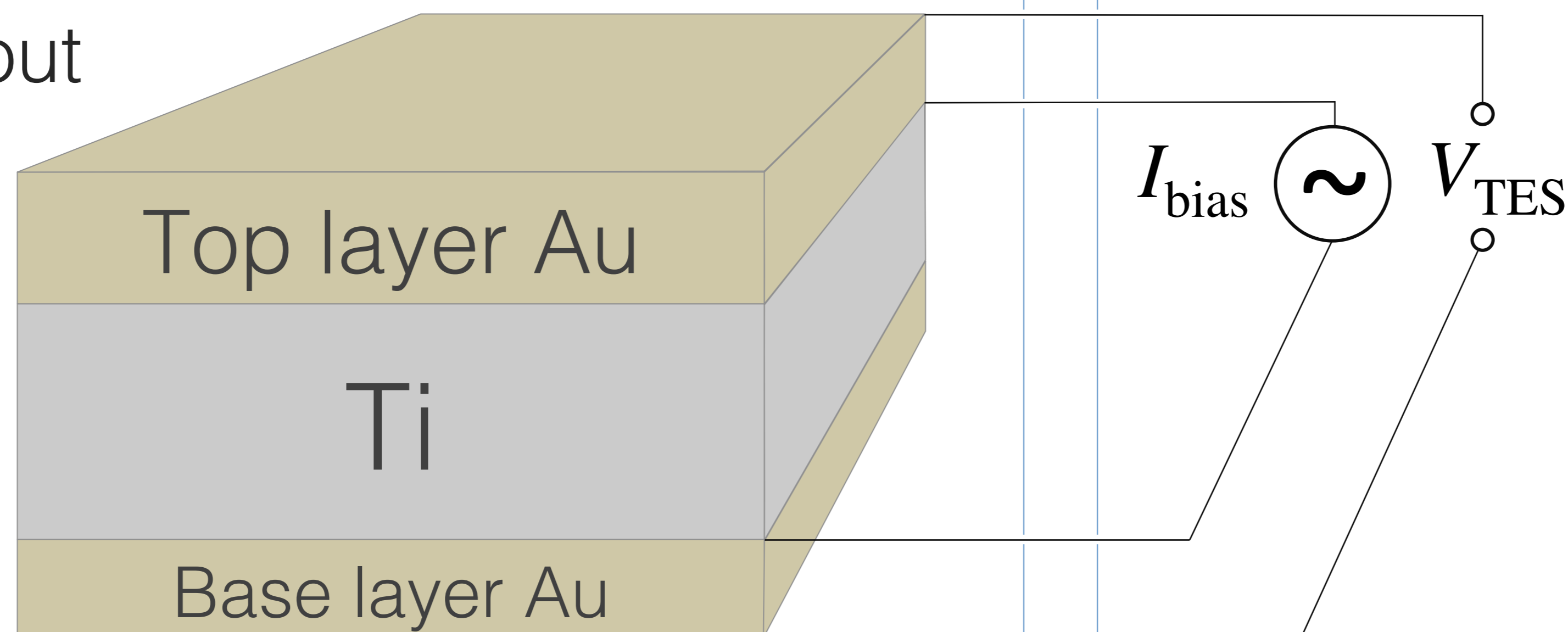


Tuning SPT-3G TES electrical properties with a trilayer Au-Ti-Au thin-film stack

Faustin W. Carter on behalf of the SPT-3G Collaboration

Trilayer film geometry

- ✧ Au-Ti-Au trilayers sputtered without breaking vacuum
- ✧ SiN substrate
- ✧ 5 nm Ti glue layer under base

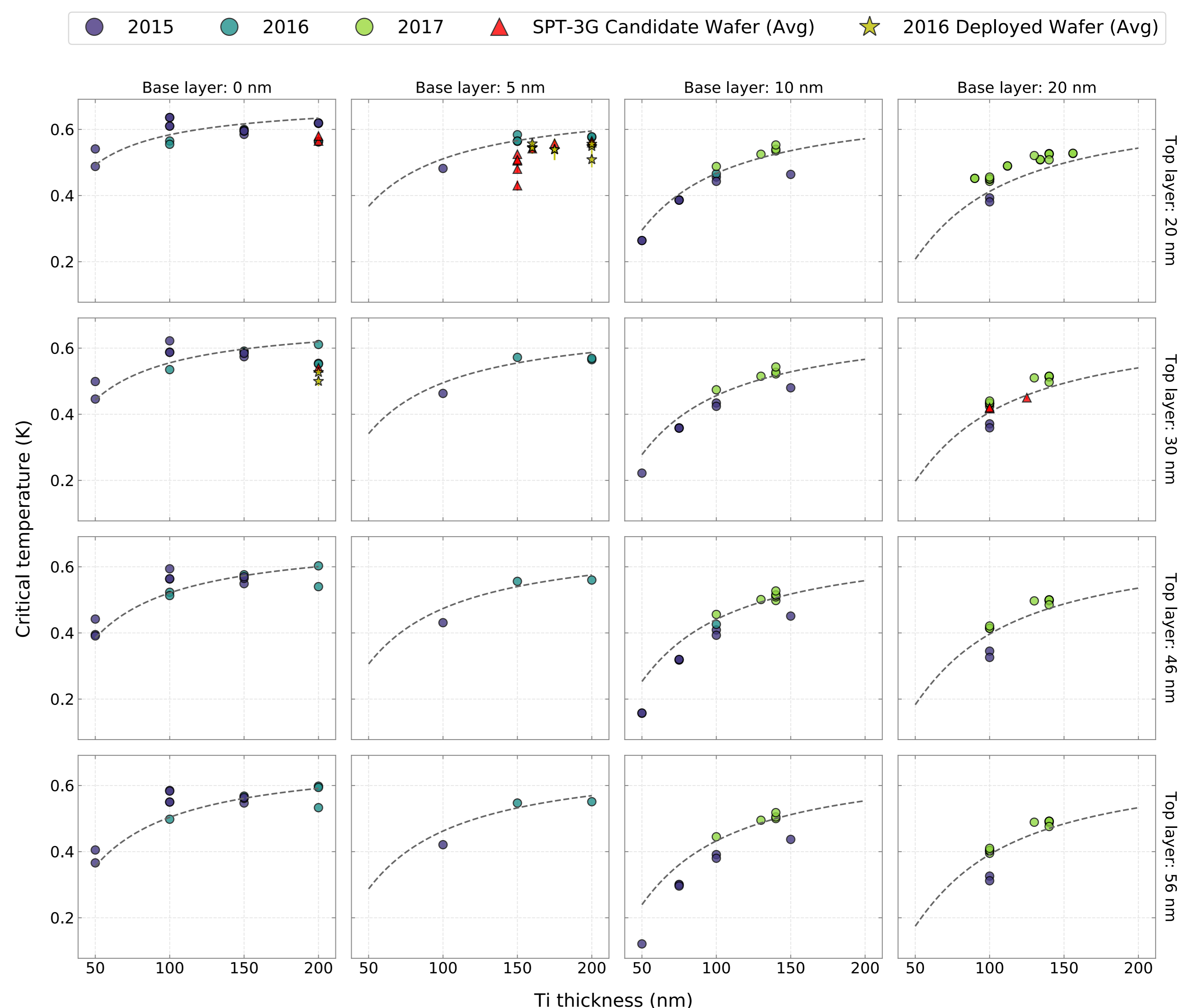


Measurement

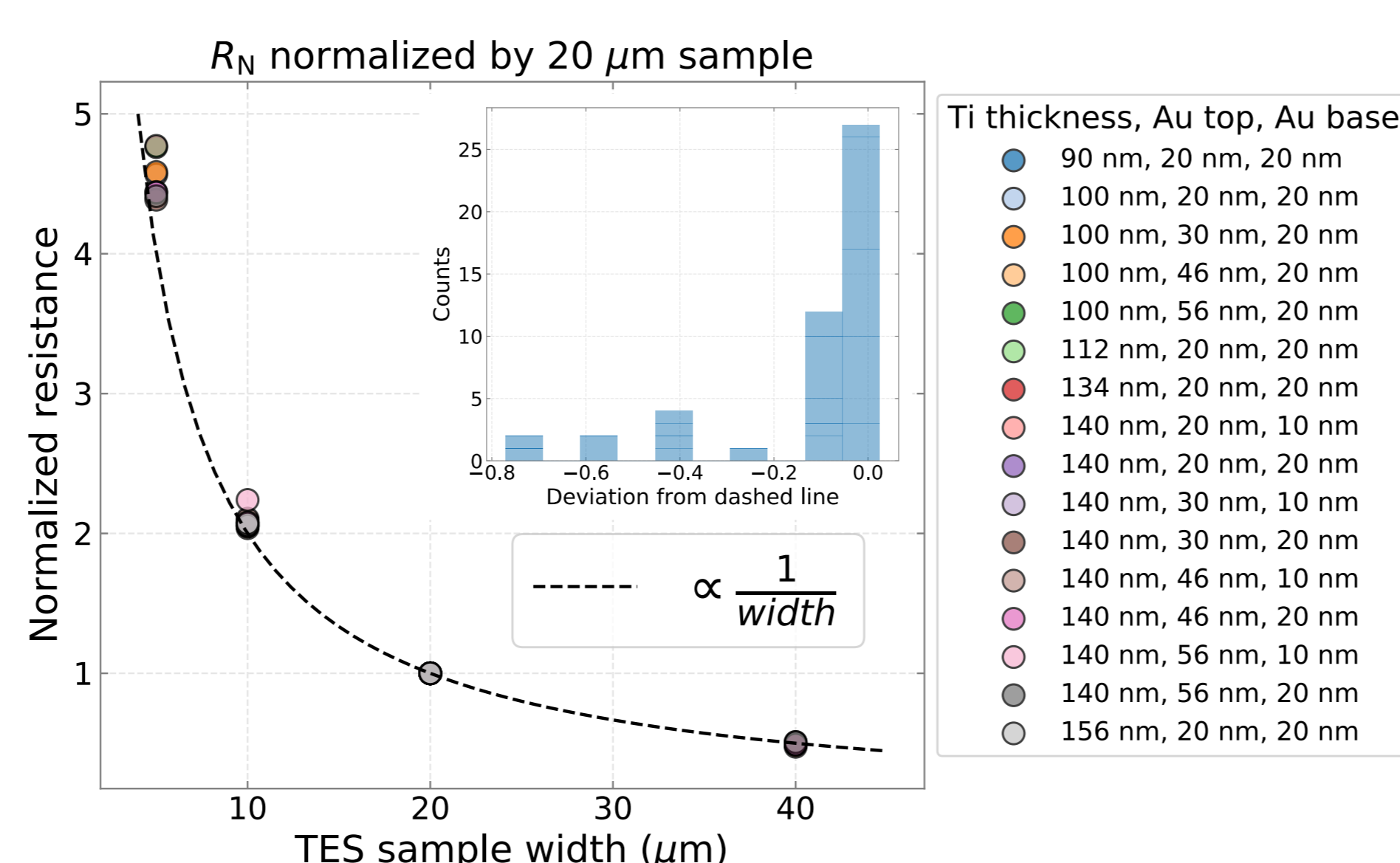
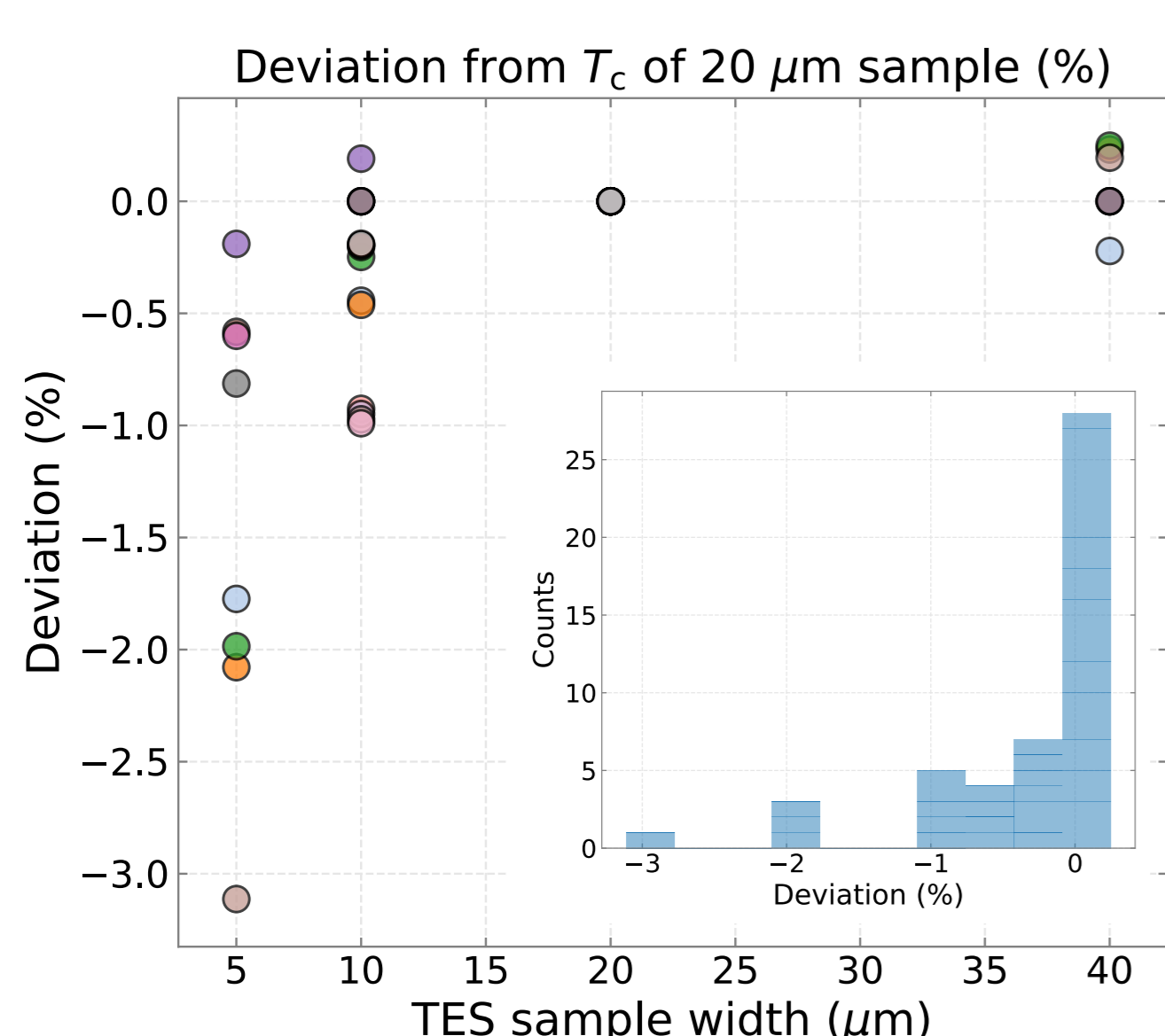
- ✧ ADR cryostat used to sweep temperature (0.1–0.7 mK)
- ✧ Four-wire resistance measured with AC bridge
- ✧ Temperature measured with RuOx sensor

Trilayer T_c dependence on film thickness

- ✧ Au-Ti-Au trilayer is modeled as a Au-Ti bilayer with an effective Au thickness that is a linear combination of trilayer Au thicknesses: $d_{\text{eff}} = d_{\text{Base}} + w d_{\text{Top}}$
- ✧ Usadel equations used to fit all data with only three free parameters:
 1. Ti T_c with no Au (680 mK)
 2. Effective $R_{\text{interface}}$
 3. Top layer weight factor w
- ✧ Effective bilayer Au thickness (d_{eff}) result is: $d_{\text{eff}} = d_{\text{Base}} + 0.16 d_{\text{Top}}$
- ✧ Systematic T_c offsets with different sputtering targets (labeled by year)



Trilayer T_c, R_N dependence on sample width



- ✧ T_c weakly depends on TES width
- ✧ R_N scales inversely with TES width

Resistance may be tuned entirely by width without regard to film thickness.